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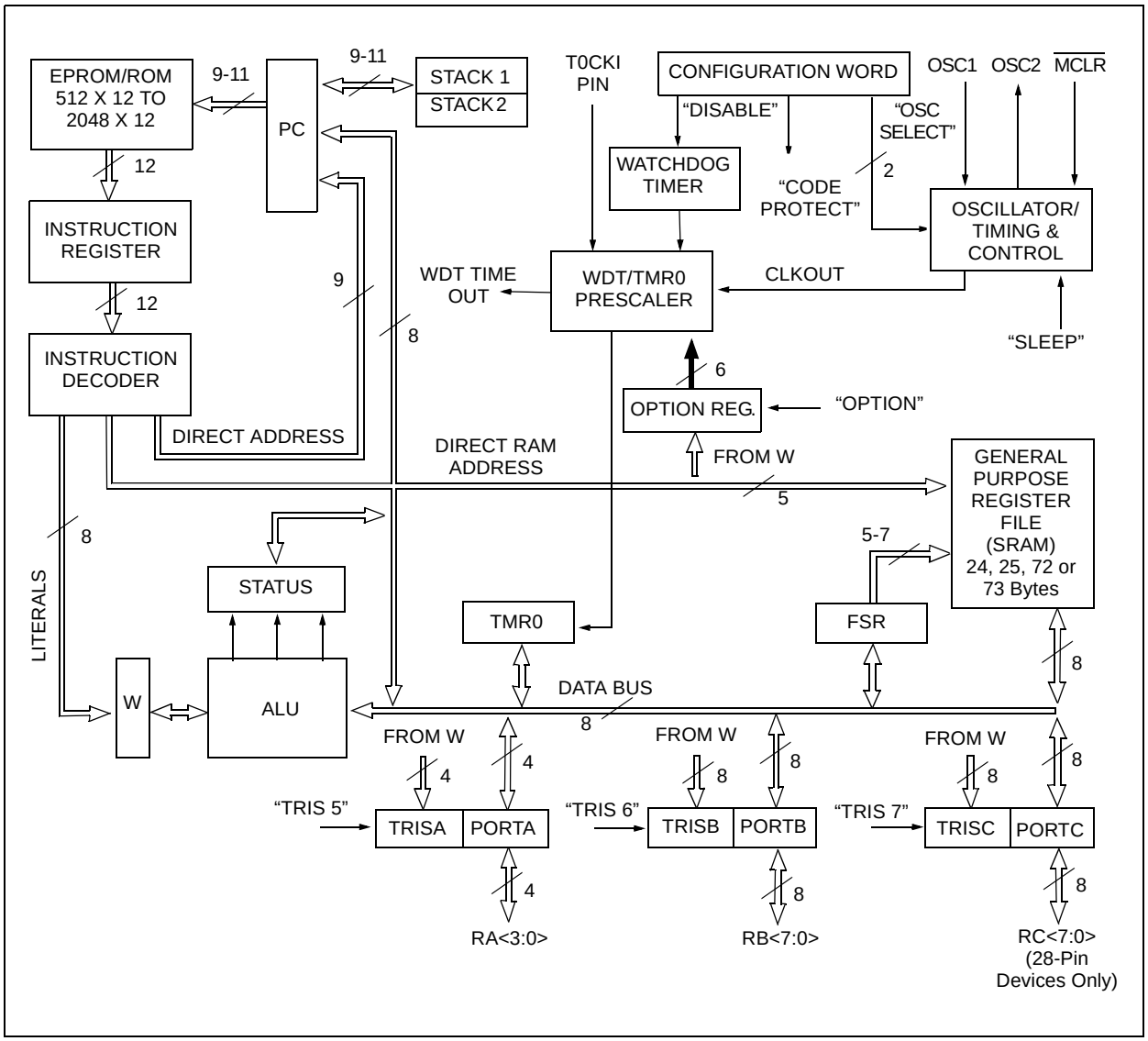
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c55a-20e-ss

FIGURE 3-1: PIC16C5X SERIES BLOCK DIAGRAM



NOTES:

6.0 MEMORY ORGANIZATION

PIC16C5X memory is organized into program memory and data memory. For devices with more than 512 bytes of program memory, a paging scheme is used. Program memory pages are accessed using one or two STATUS Register bits. For devices with a data memory register file of more than 32 registers, a banking scheme is used. Data memory banks are accessed using the File Selection Register (FSR).

6.1 Program Memory Organization

The PIC16C54, PIC16CR54 and PIC16C55 have a 9-bit Program Counter (PC) capable of addressing a 512 x 12 program memory space (Figure 6-1). The PIC16C56 and PIC16CR56 have a 10-bit Program Counter (PC) capable of addressing a 1K x 12 program memory space (Figure 6-2). The PIC16CR57, PIC16C58 and PIC16CR58 have an 11-bit Program Counter capable of addressing a 2K x 12 program memory space (Figure 6-3). Accessing a location above the physically implemented address will cause a wraparound.

A NOP at the RESET vector location will cause a restart at location 000h. The RESET vector for the PIC16C54, PIC16CR54 and PIC16C55 is at 1FFh. The RESET vector for the PIC16C56 and PIC16CR56 is at 3FFh. The RESET vector for the PIC16C57, PIC16CR57, PIC16C58, and PIC16CR58 is at 7FFh. See Section 6.5 for additional information using CALL and GOTO instructions.

FIGURE 6-1: PIC16C54/CR54/C55 PROGRAM MEMORY MAP AND STACK

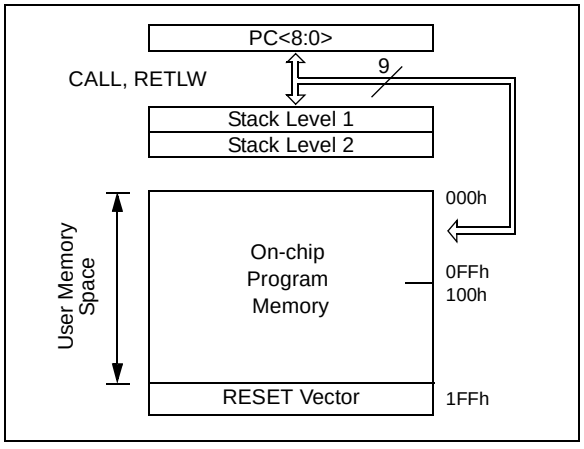


FIGURE 6-2: PIC16C56/CR56 PROGRAM MEMORY MAP AND STACK

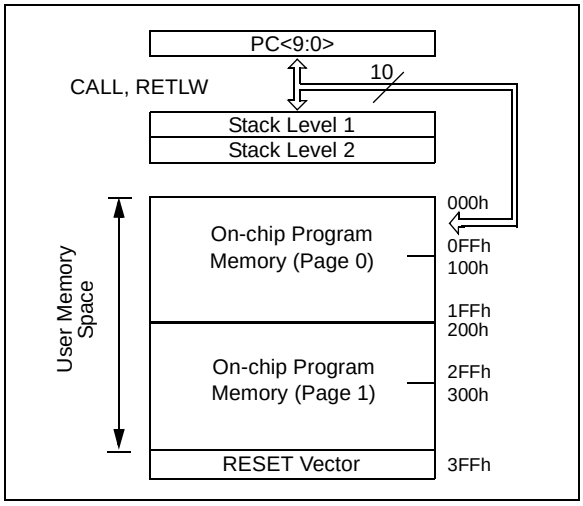


FIGURE 6-3: PIC16C57/CR57/C58/ CR58 PROGRAM MEMORY MAP AND STACK

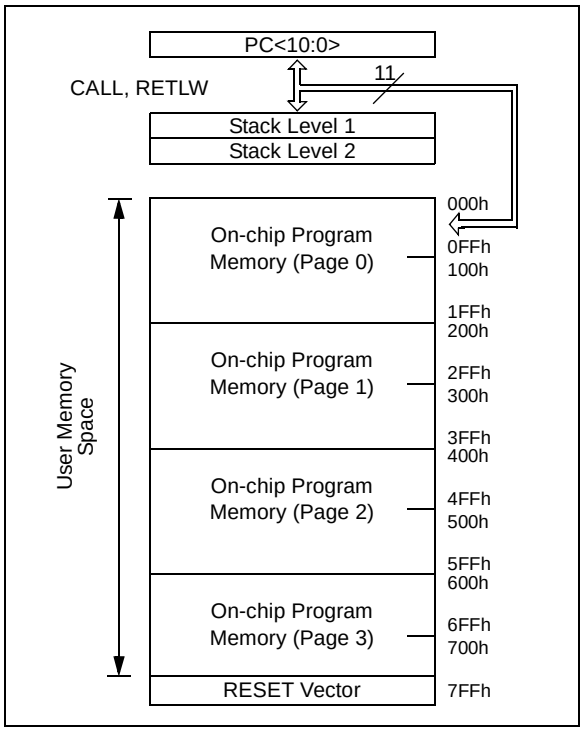
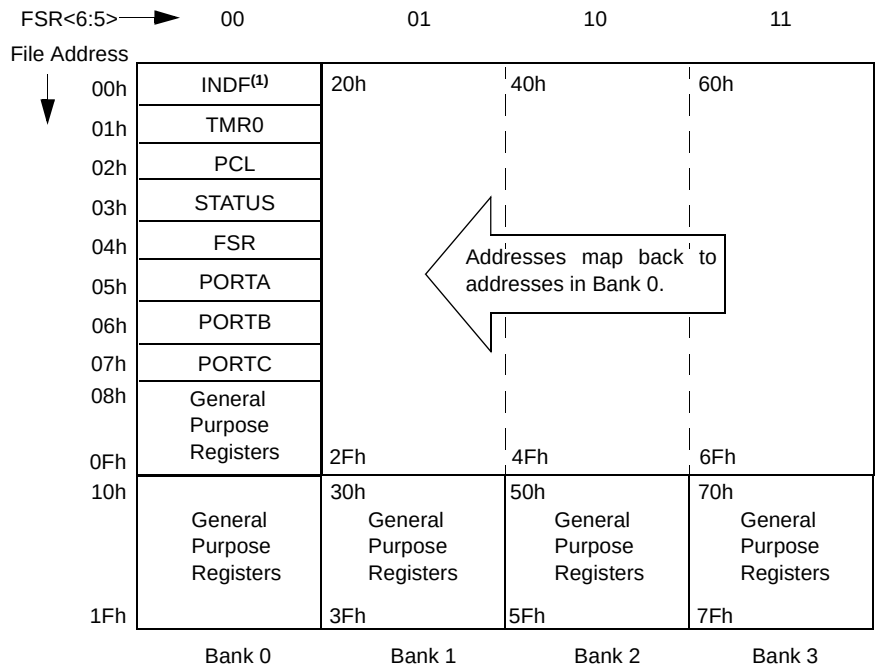
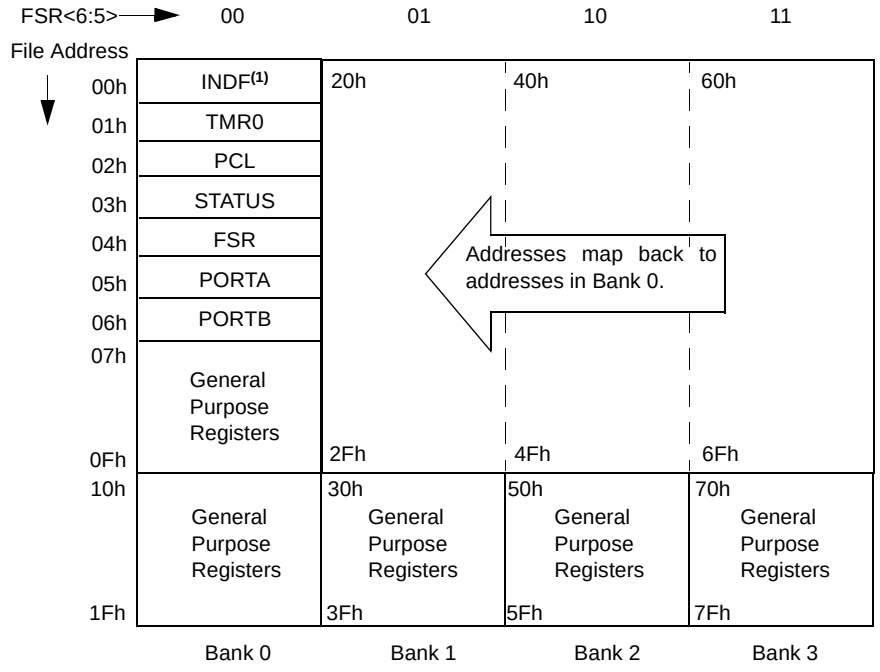


FIGURE 6-5: PIC16C57/CR57 REGISTER FILE MAP



Note 1: Not a physical register. See Section 6.7.

FIGURE 6-6: PIC16C58/CR58 REGISTER FILE MAP



Note 1: Not a physical register. See Section 6.7.

NOTES:

9.0 SPECIAL FEATURES OF THE CPU

What sets a microcontroller apart from other processors are special circuits that deal with the needs of real-time applications. The PIC16C5X family of microcontrollers have a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These features are:

- Oscillator Selection (Section 4.0)
- RESET (Section 5.0)
- Power-On Reset (Section 5.1)
- Device Reset Timer (Section 5.2)
- Watchdog Timer (WDT) (Section 9.2)
- SLEEP (Section 9.3)
- Code protection (Section 9.4)
- ID locations (Section 9.5)

The PIC16C5X Family has a Watchdog Timer which can be shut off only through configuration bit WDTE. It runs off of its own RC oscillator for added reliability. There is an 18 ms delay provided by the Device Reset Timer (DRT), intended to keep the chip in RESET until the crystal oscillator is stable. With this timer on-chip, most applications need no external RESET circuitry.

The SLEEP mode is designed to offer a very low current Power-down mode. The user can wake up from SLEEP through external RESET or through a Watchdog Timer time-out. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select various options.

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (f) – (W) → (dest)

Status Affected: C, DC, Z

Encoding:

0000	10df	ffff

Description: Subtract (2's complement method) the W register from register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example 1: `SUBWF REG1, 1`

Before Instruction
REG1 = 3
W = 2
C = ?
After Instruction
REG1 = 1
W = 2
C = 1 ; result is positive

Example 2:
Before Instruction
REG1 = 2
W = 2
C = ?
After Instruction
REG1 = 0
W = 2
C = 1 ; result is zero

Example 3:
Before Instruction
REG1 = 1
W = 2
C = ?
After Instruction
REG1 = 0xFF
W = 2
C = 0 ; result is negative

SWAPF **Swap Nibbles in f**

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (f<3:0>) → (dest<7:4>);
(f<7:4>) → (dest<3:0>)

Status Affected: None

Encoding:

0011	10df	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0 the result is placed in W register. If 'd' is 1 the result is placed in register 'f'.

Words: 1

Cycles: 1

Example `SWAPF REG1, 0`

Before Instruction
REG1 = 0xA5
After Instruction
REG1 = 0xA5
W = 0x5A

TRIS **Load TRIS Register**

Syntax: [*label*] TRIS f

Operands: f = 5, 6 or 7

Operation: (W) → TRIS register f

Status Affected: None

Encoding:

0000	0000	0fff

Description: TRIS register 'f' (f = 5, 6, or 7) is loaded with the contents of the W register.

Words: 1

Cycles: 1

Example `TRIS PORTB`

Before Instruction
W = 0xA5
After Instruction
TRISB = 0xA5

12.4 DC Characteristics: PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial) PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D030	VIL	**Input Low Voltage**					
		I/O ports	VSS	—	0.2 VDD	V	Pin at hi-impedance
		MCLR (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		T0CKI (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		OSC1 (Schmitt Trigger)	VSS	—	0.15 VDD	V	PIC16C5X-RC only(3)
		OSC1 (Schmitt Trigger)	VSS	—	0.3 VDD	V	PIC16C5X-XT, 10, HS, LP
D040	VIH	**Input High Voltage**					
		I/O ports	0.45 VDD	—	VDD	V	For all VDD(4)
		I/O ports	2.0	—	VDD	V	4.0V < VDD ≤ 5.5V(4)
		I/O ports	0.36 VDD	—	VDD	V	VDD > 5.5V
		MCLR (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		T0CKI (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		OSC1 (Schmitt Trigger)	0.85 VDD	—	VDD	V	PIC16C5X-RC only(3)
		OSC1 (Schmitt Trigger)	0.7 VDD	—	VDD	V	PIC16C5X-XT, 10, HS, LP
D050	VHYS	**Hysteresis of Schmitt Trigger inputs**	0.15 VDD*	—	—	V	
D060	IIL	**Input Leakage Current(1,2)**					**For VDD ≤ 5.5V:**
		I/O ports	–1	0.5	+1	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
		MCLR	–5	—	—	µA	VPIN = VSS + 0.25V
		MCLR	—	0.5	+5	µA	VPIN = VDD
		T0CKI	–3	0.5	+3	µA	VSS ≤ VPIN ≤ VDD
		OSC1	–3	0.5	+3	µA	VSS ≤ VPIN ≤ VDD, PIC16C5X-XT, 10, HS, LP
D080	VOL	**Output Low Voltage**					
		I/O ports	—	—	0.6	V	IOL = 8.7 mA, VDD = 4.5V
		OSC2/CLKOUT	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, PIC16C5X-RC
D090	VOH	**Output High Voltage(2)**					
		I/O ports	VDD – 0.7	—	—	V	IOH = –5.4 mA, VDD = 4.5V
		OSC2/CLKOUT	VDD – 0.7	—	—	V	IOH = –1.0 mA, VDD = 4.5V, PIC16C5X-RC

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For PIC16C5X-RC devices, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

12.5 DC Characteristics: PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D030	VIL	**Input Low Voltage**					
		I/O ports	Vss	—	0.15 VDD	V	Pin at hi-impedance
		MCLR (Schmitt Trigger)	Vss	—	0.15 VDD	V	
		T0CKI (Schmitt Trigger)	Vss	—	0.15 VDD	V	
		OSC1 (Schmitt Trigger)	Vss	—	0.15 VDD	V	PIC16C5X-RC only(3)
		OSC1 (Schmitt Trigger)	Vss	—	0.3 VDD	V	PIC16C5X-XT, 10, HS, LP
D040	VIH	**Input High Voltage**					
		I/O ports	0.45 VDD	—	VDD	V	For all VDD(4)
		I/O ports	2.0	—	VDD	V	4.0V < VDD ≤ 5.5V(4)
		I/O ports	0.36 VDD	—	VDD	V	VDD > 5.5 V
		MCLR (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		T0CKI (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		OSC1 (Schmitt Trigger)	0.85 VDD	—	VDD	V	PIC16C5X-RC only(3)
		OSC1 (Schmitt Trigger)	0.7 VDD	—	VDD	V	PIC16C5X-XT, 10, HS, LP
D050	VHYS	**Hysteresis of Schmitt Trigger inputs**	0.15 VDD*	—	—	V	
D060	IIL	**Input Leakage Current (1,2)**					**For VDD ≤ 5.5 V:**
		I/O ports	–1	0.5	+1	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
		MCLR	–5	—	—	µA	VPIN = VSS + 0.25V
		MCLR	—	0.5	+5	µA	VPIN = VDD
		T0CKI	–3	0.5	+3	µA	VSS ≤ VPIN ≤ VDD
		OSC1	–3	0.5	+3	µA	VSS ≤ VPIN ≤ VDD, PIC16C5X-XT, 10, HS, LP
D080	VOL	**Output Low Voltage**					
		I/O ports	—	—	0.6	V	IOL = 8.7 mA, VDD = 4.5V
		OSC2/CLKOUT	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, PIC16C5X-RC
D090	VOH	**Output High Voltage(2)**					
		I/O ports	VDD – 0.7	—	—	V	IOH = –5.4 mA, VDD = 4.5V
		OSC2/CLKOUT	VDD – 0.7	—	—	V	IOH = –1.0 mA, VDD = 4.5V, PIC16C5X-RC

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the $\overline{\text{MCLR}}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For PIC16C5X-RC devices, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

13.5 Timing Parameter Symbology and Load Conditions

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T	
F Frequency	T Time

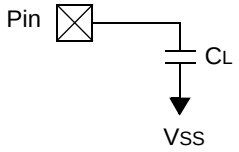
Lowercase letters (pp) and their meanings:

pp	
2 to	mc $\overline{\text{MCLR}}$
ck CLKOUT	osc oscillator
cy cycle time	os OSC1
drt device reset timer	t0 T0CKI
io I/O port	wdt watchdog timer

Uppercase letters and their meanings:

S	
F Fall	P Period
H High	R Rise
I Invalid (Hi-impedance)	V Valid
L Low	Z Hi-impedance

FIGURE 13-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS - PIC16CR54A



C_L = 50 pF for all pins and OSC2 for RC modes

0 -15 pF for OSC2 in XT, HS or LP modes when external clock is used to drive OSC1

14.0 DEVICE CHARACTERIZATION - PIC16C54A

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 14-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

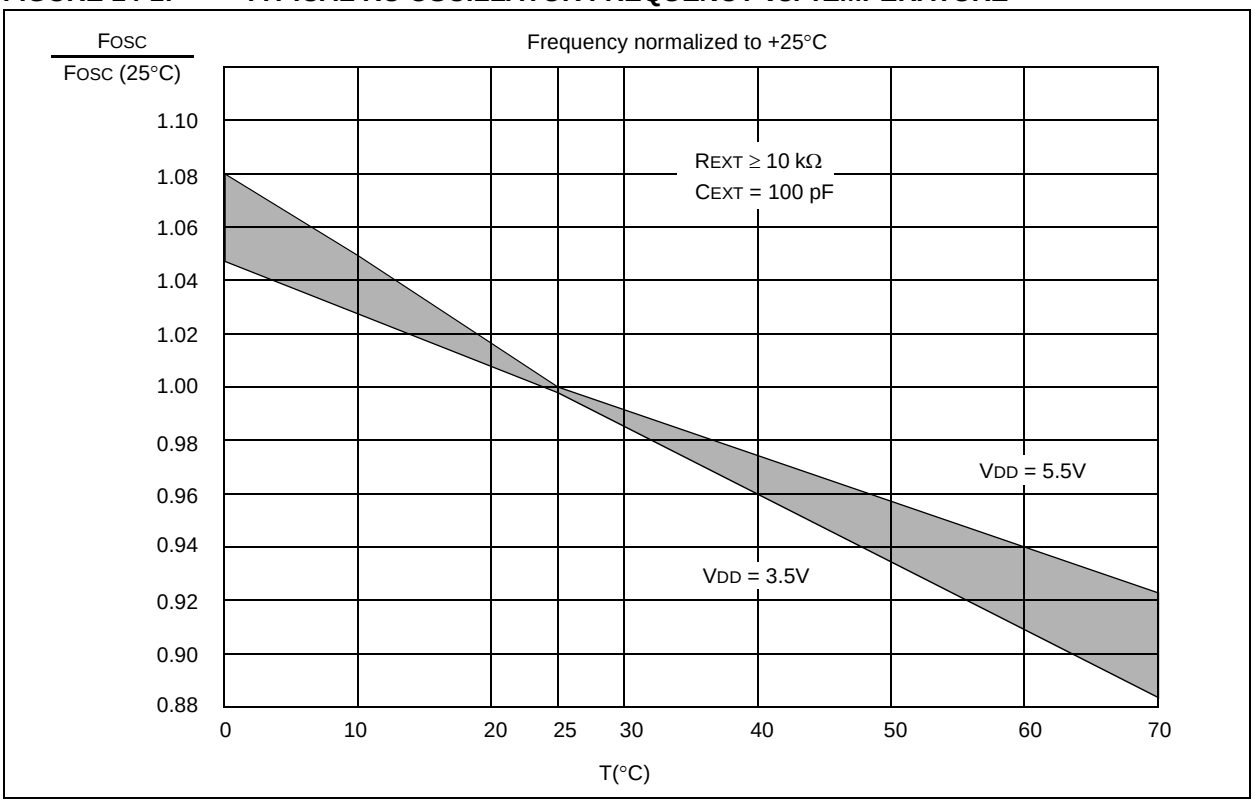


TABLE 14-1: RC OSCILLATOR FREQUENCIES

CEXT	REXT	Average FOSC @ 5 V, 25°C	
20 pF	3.3K	5 MHz	± 27%
	5K	3.8 MHz	± 21%
	10K	2.2 MHz	± 21%
	100K	262 kHz	± 31%
100 pF	3.3K	1.6 MHz	± 13%
	5K	1.2 MHz	± 13%
	10K	684 kHz	± 18%
	100K	71 kHz	± 25%
300 pF	3.3K	660 kHz	± 10%
	5.0K	484 kHz	± 14%
	10K	267 kHz	± 15%
	100K	29 kHz	± 19%

The frequencies are measured on DIP packages.

The percentage variation indicated here is part-to-part variation due to normal process distribution. The variation indicated is ±3 standard deviations from the average value for VDD = 5V.

15.1 DC Characteristics: PIC16C54A-04, 10, 20 (Commercial) PIC16C54A-04I, 10I, 20I (Industrial) PIC16LC54A-04 (Commercial) PIC16LC54A-04I (Industrial)

PIC16LC54A-04 **PIC16LC54A-04I** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
PIC16C54A-04, 10, 20 **PIC16C54A-04I, 10I, 20I** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		PIC16LC54A	3.0 2.5	— —	6.25 6.25	V V	XT and RC modes LP mode
D001A		PIC16C54A	3.0 4.5	— —	6.25 5.5	V V	RC, XT and LP modes HS mode
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D005	IDD	**Supply Current(2)**					
		PIC16LC5X	— — —	0.5 11 11	2.5 27 35	mA µA µA	FOSC = 4.0 MHz, VDD = 5.5V, RC(3) and XT modes FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Commercial FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Industrial
D005A		PIC16C5X	— — — — —	1.8 2.4 4.5 14 17	2.4 8.0 16 29 37	mA mA mA µA µA	FOSC = 4.0 MHz, VDD = 5.5V, RC(3) and XT modes FOSC = 10 MHz, VDD = 5.5V, HS mode FOSC = 20 MHz, VDD = 5.5V, HS mode FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode, Commercial FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

15.6 Timing Diagrams and Specifications

FIGURE 15-2: EXTERNAL CLOCK TIMING - PIC16C54A

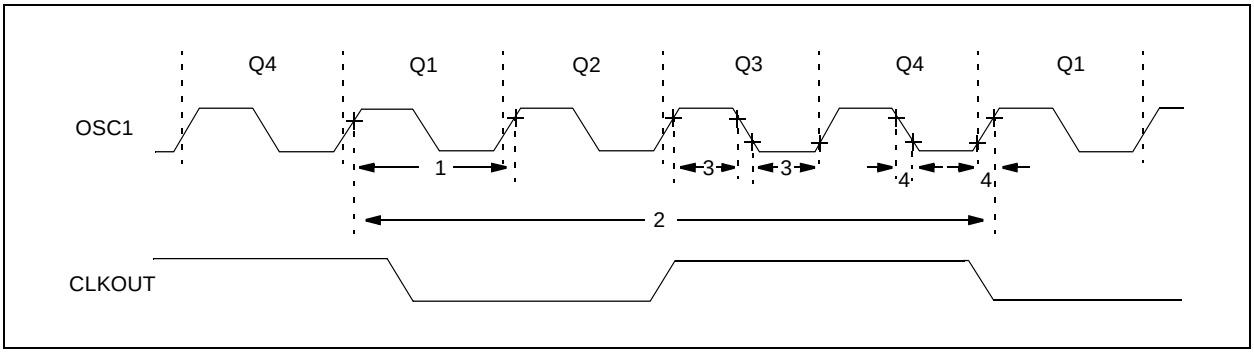


TABLE 15-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54A

AC Characteristics		Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –20°C ≤ TA ≤ +85°C for industrial - PIC16LV54A-02I –40°C ≤ TA ≤ +125°C for extended					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	FOSC	External CLKIN Frequency(1)	DC	—	4.0	MHz	XT osc mode
			DC	—	2.0	MHz	XT osc mode (PIC16LV54A)
			DC	—	4.0	MHz	HS osc mode (04)
			DC	—	10	MHz	HS osc mode (10)
			DC	—	20	MHz	HS osc mode (20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency(1)	DC	—	4.0	MHz	RC osc mode
			DC	—	2.0	MHz	RC osc mode (PIC16LV54A)
			0.1	—	4.0	MHz	XT osc mode
			0.1	—	2.0	MHz	XT osc mode (PIC16LV54A)
			4.0	—	4.0	MHz	HS osc mode (04)
			4.0	—	10	MHz	HS osc mode (10)
			4.0	—	20	MHz	HS osc mode (20)
			5.0	—	200	kHz	LP osc mode

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.
When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

FIGURE 16-2: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 20 pF, 25°C

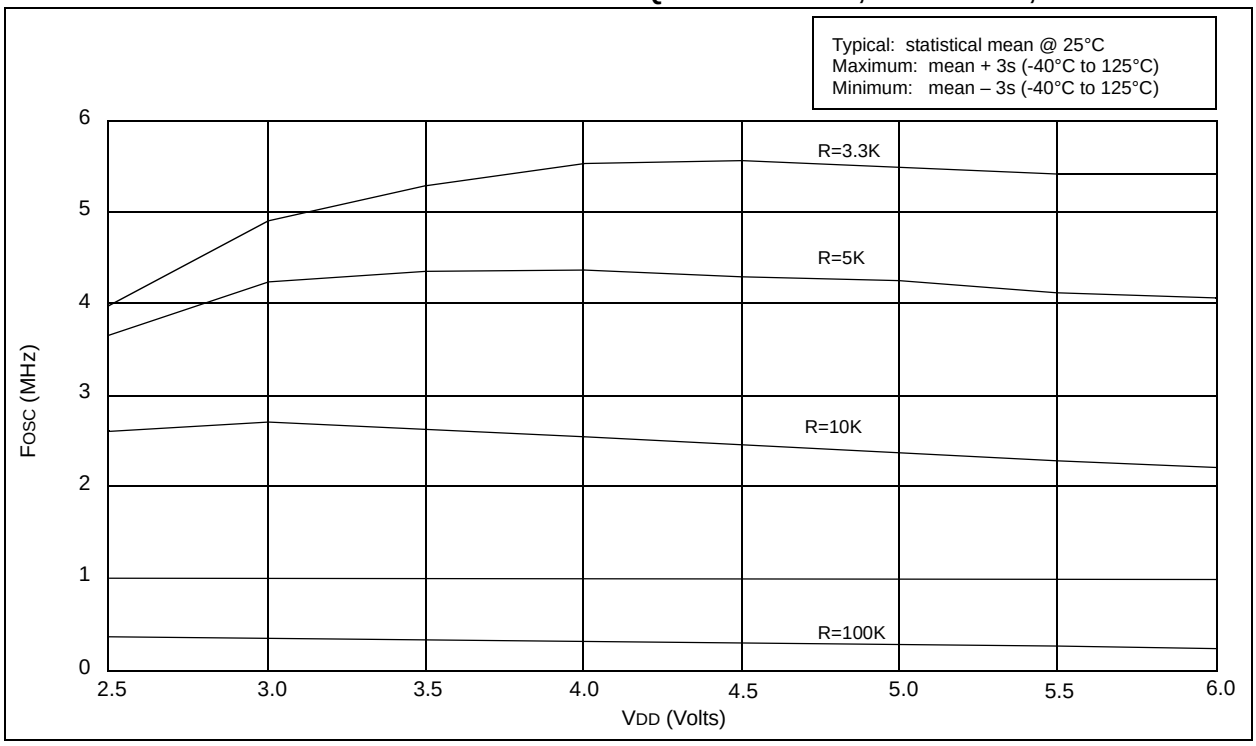


FIGURE 16-3: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 100 pF, 25°C

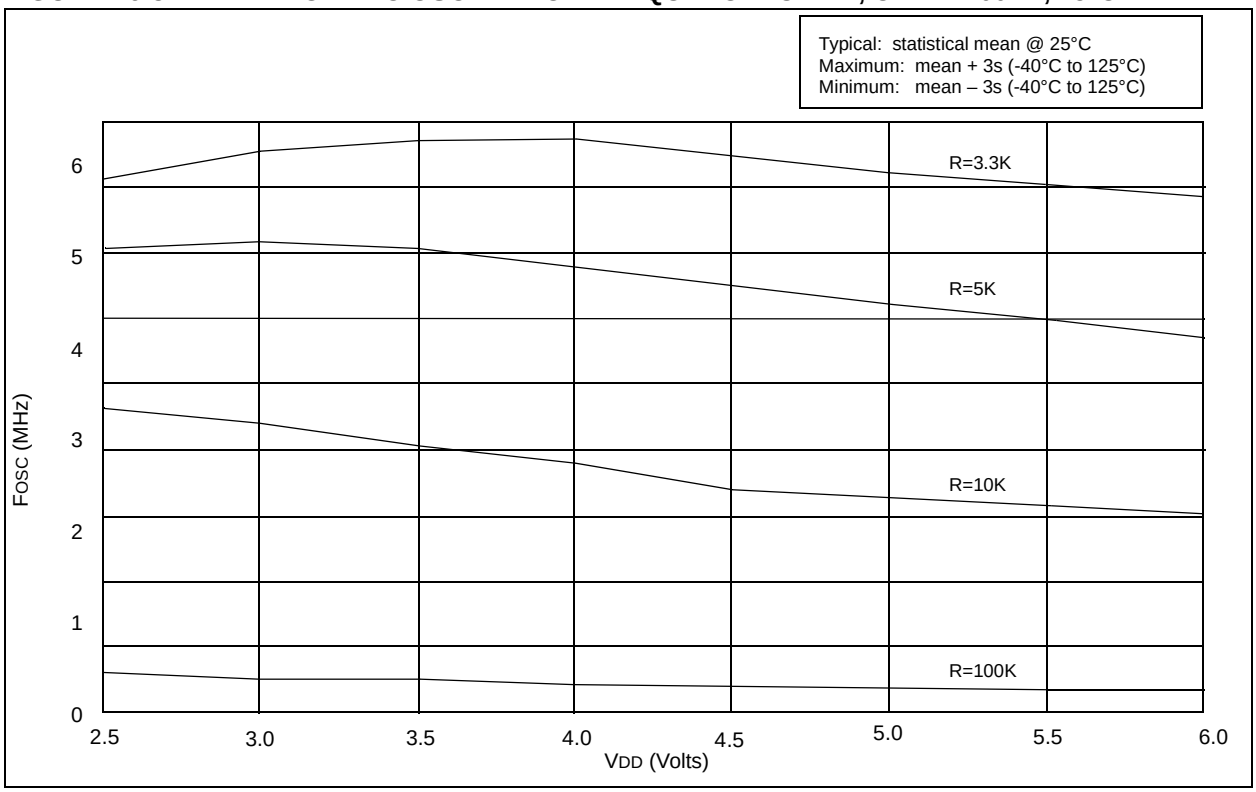
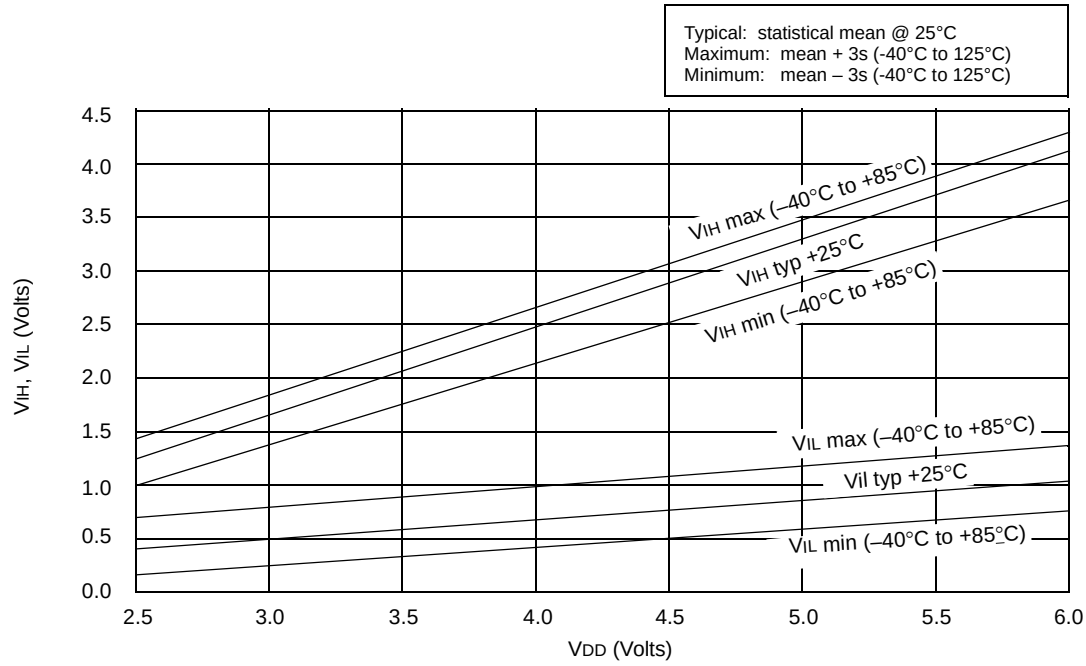


FIGURE 16-9: VIH, VIL OF $\overline{\text{MCLR}}$, T0CKI AND OSC1 (IN RC MODE) vs. VDD



Note: These input pins have Schmitt Trigger input buffers.

FIGURE 16-14: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 pF, 25°C)

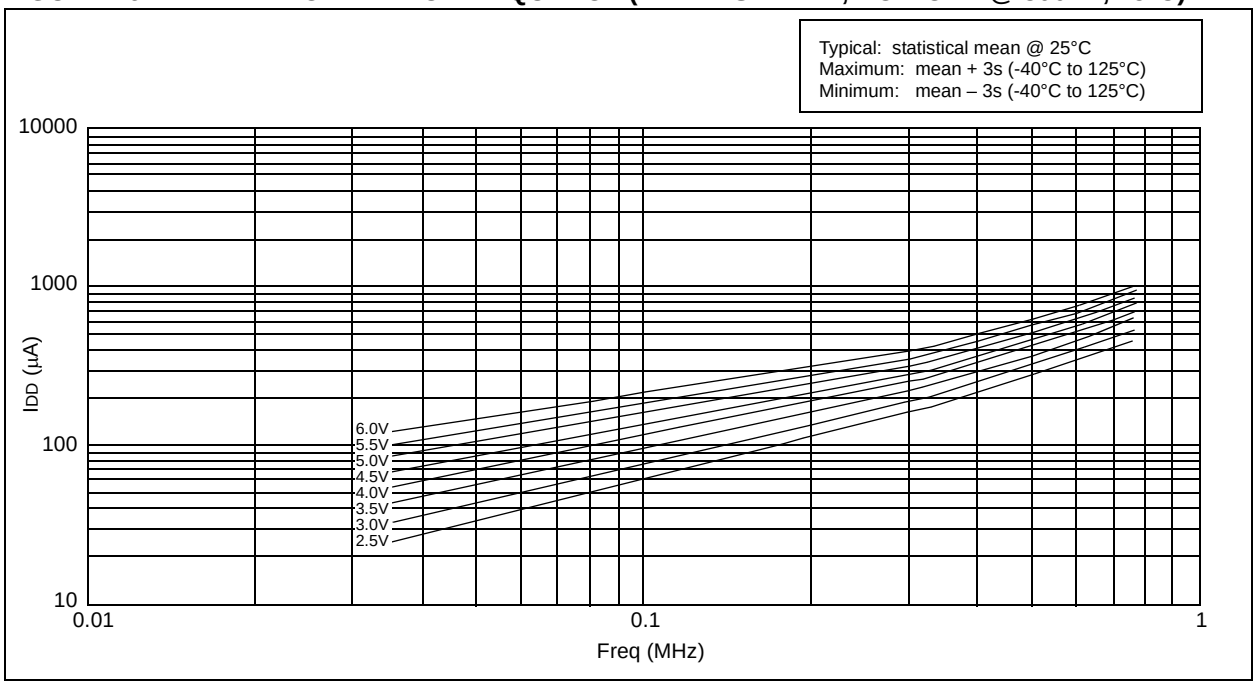
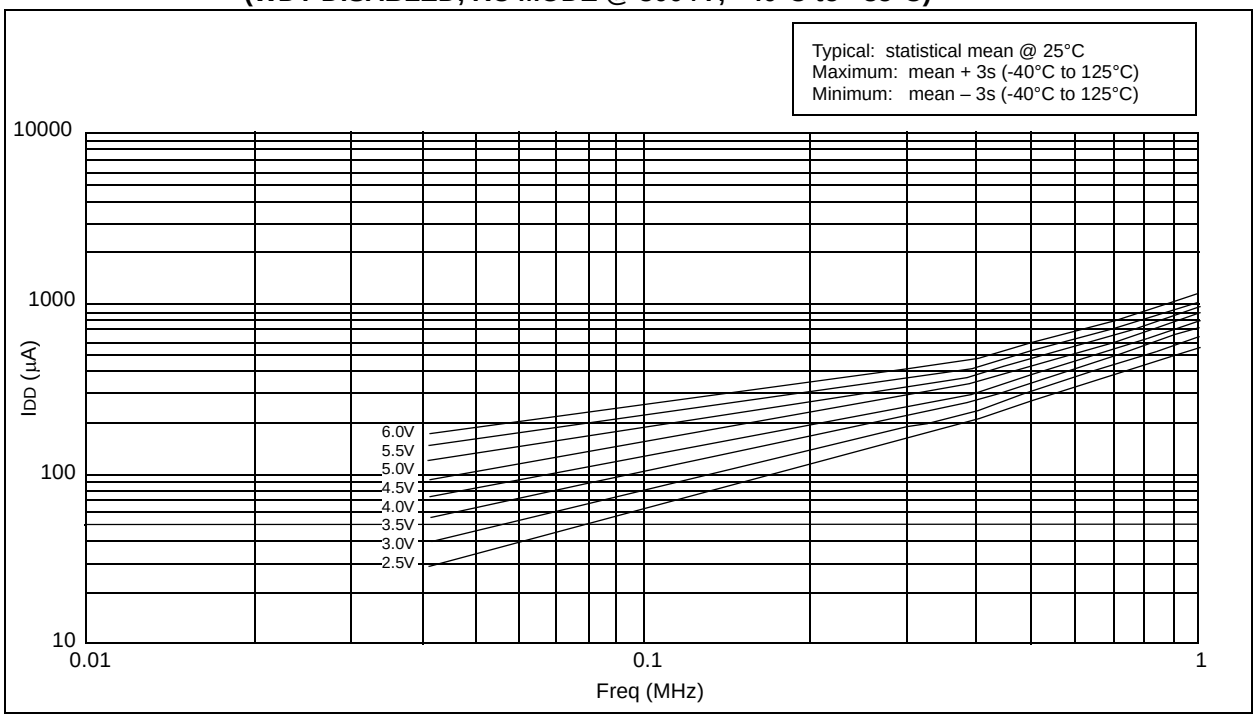


FIGURE 16-15: MAXIMUM IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 pF, –40°C to +85°C)



17.1 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial)
PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial)
PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial)
PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC5X **PIC16LCR5X** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
PIC16C5X **PIC16CR5X** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	IDD	**Supply Current(2,3)**					
D010		PIC16LC5X	—	0.5	2.4	mA	FOSC = 4.0 MHz, VDD = 5.5V, XT and RC modes
			—	11	27	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Commercial
			—	14	35	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Industrial
D010A		PIC16C5X	—	1.8	2.4	mA	FOSC = 4 MHz, VDD = 5.5V, XT and RC modes
			—	2.6	3.6*	mA	
			—	4.5	16	mA	FOSC = 10 MHz, VDD = 3.0V, HS mode
			—	14	32	µA	FOSC = 20 MHz, VDD = 5.5V, HS mode
			—	17	40	µA	FOSC = 32 kHz, VDD = 3.0V, LP mode, Commercial
							FOSC = 32 kHz, VDD = 3.0V, LP mode, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

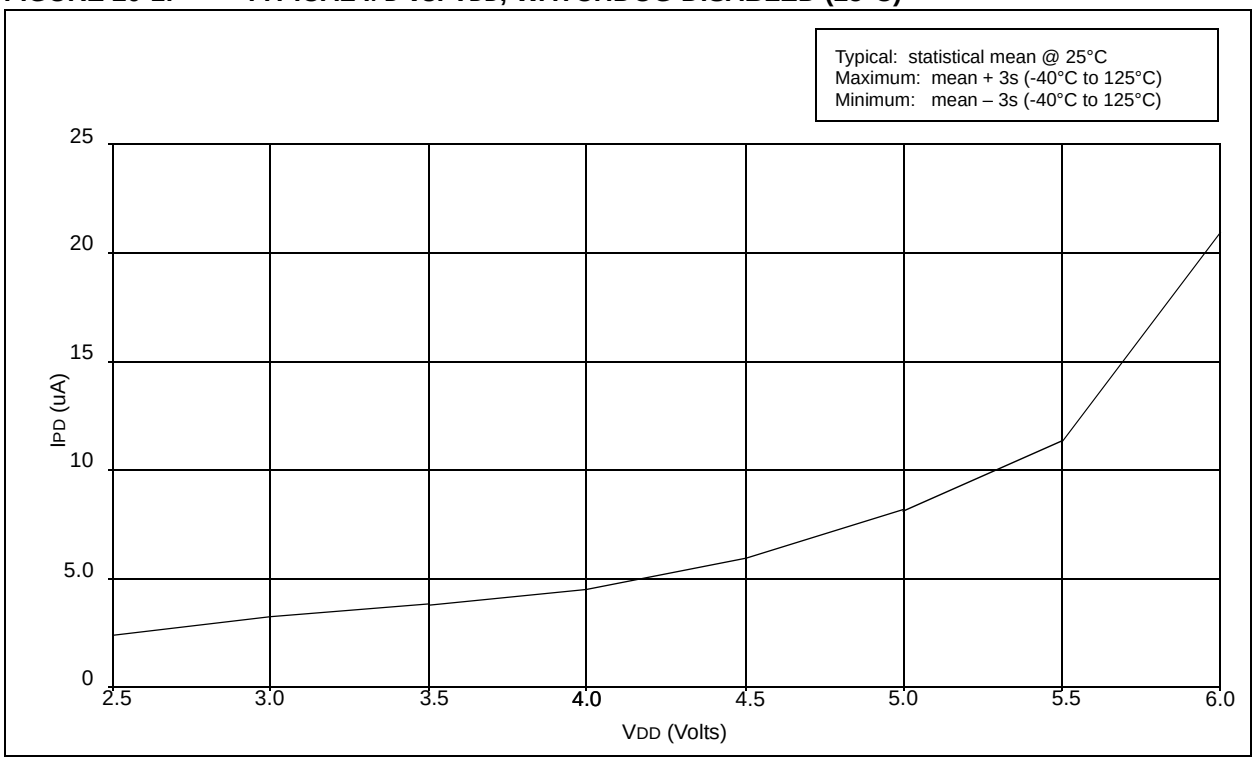
3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

20.0 DEVICE CHARACTERIZATION - PIC16LC54C 40MHz

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

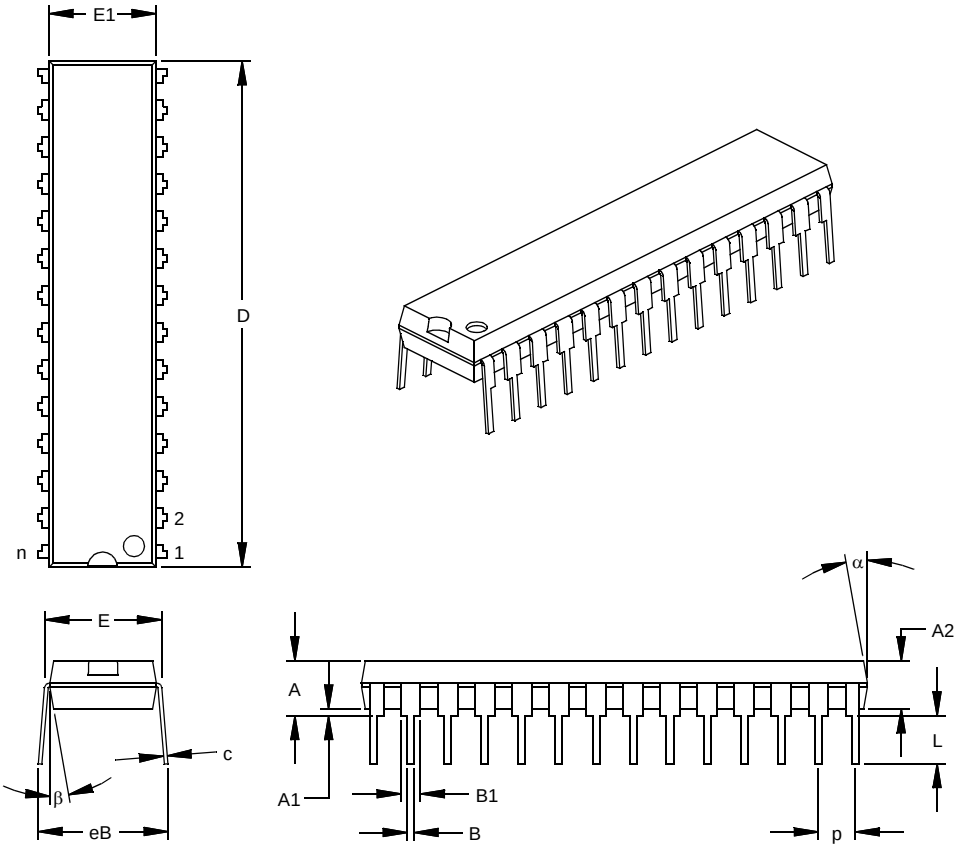
"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 20-1: TYPICAL IPD vs. VDD, WATCHDOG DISABLED (25°C)



28-Lead Skinny Plastic Dual In-line (SP) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.150	.160	3.56	3.81	4.06
Molded Package Thickness	A2	.125	.130	.135	3.18	3.30	3.43
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.310	.325	7.62	7.87	8.26
Molded Package Width	E1	.275	.285	.295	6.99	7.24	7.49
Overall Length	D	1.345	1.365	1.385	34.16	34.67	35.18
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.040	.053	.065	1.02	1.33	1.65
Lower Lead Width	B	.016	.019	.022	0.41	0.48	0.56
Overall Row Spacing §	eB	.320	.350	.430	8.13	8.89	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic
Notes:
Dimension D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-095
Drawing No. C04-070

W

X

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